

# MIKRO Project: 03SF0419A

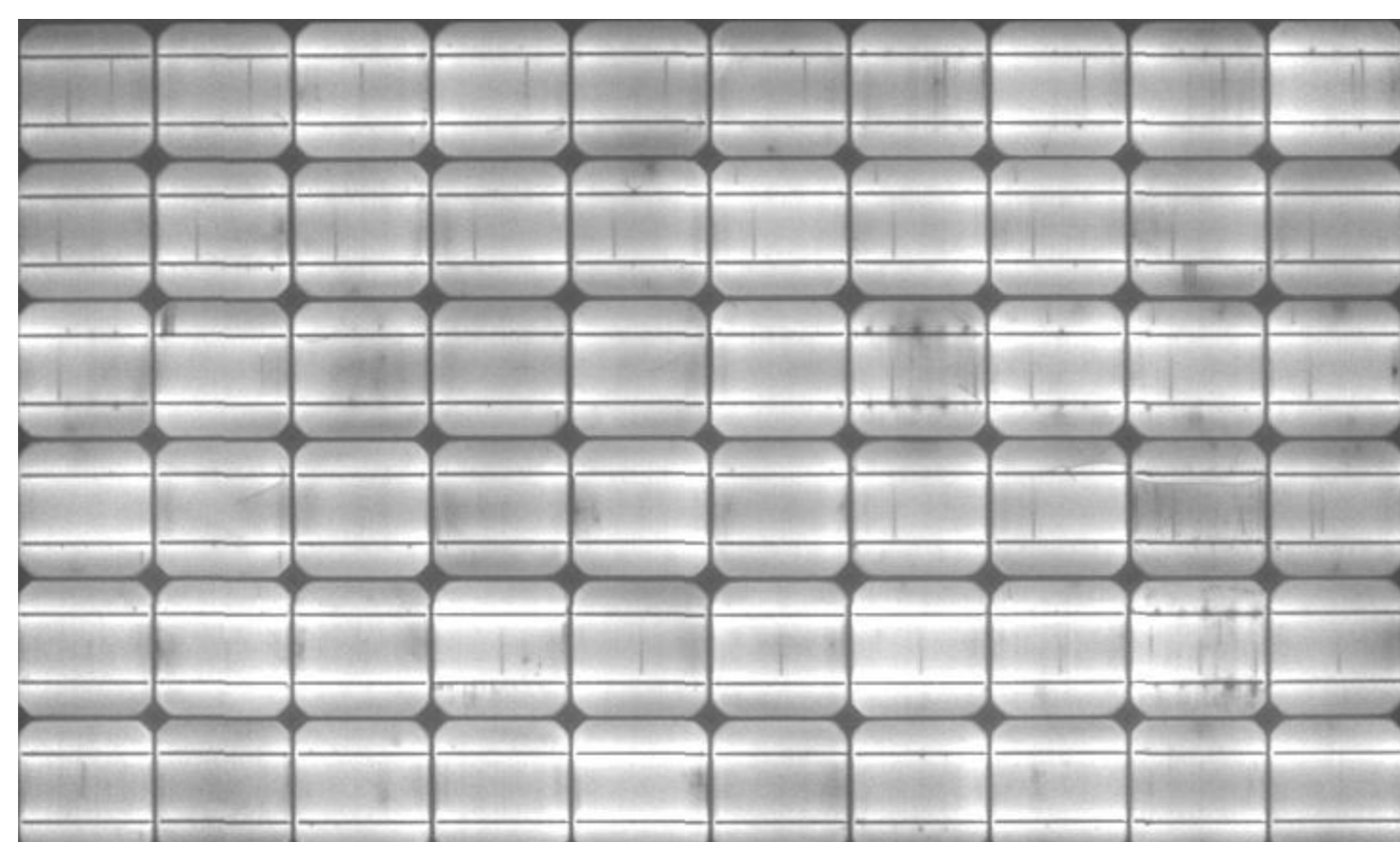
## Micro crack formation in PV-modules

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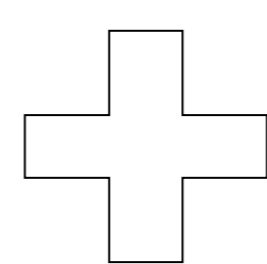
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### Motivation

#### Micro cracks from production

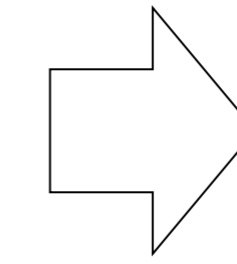


- Micro cracks can be initiated e.g. during soldering of cell interconnectors

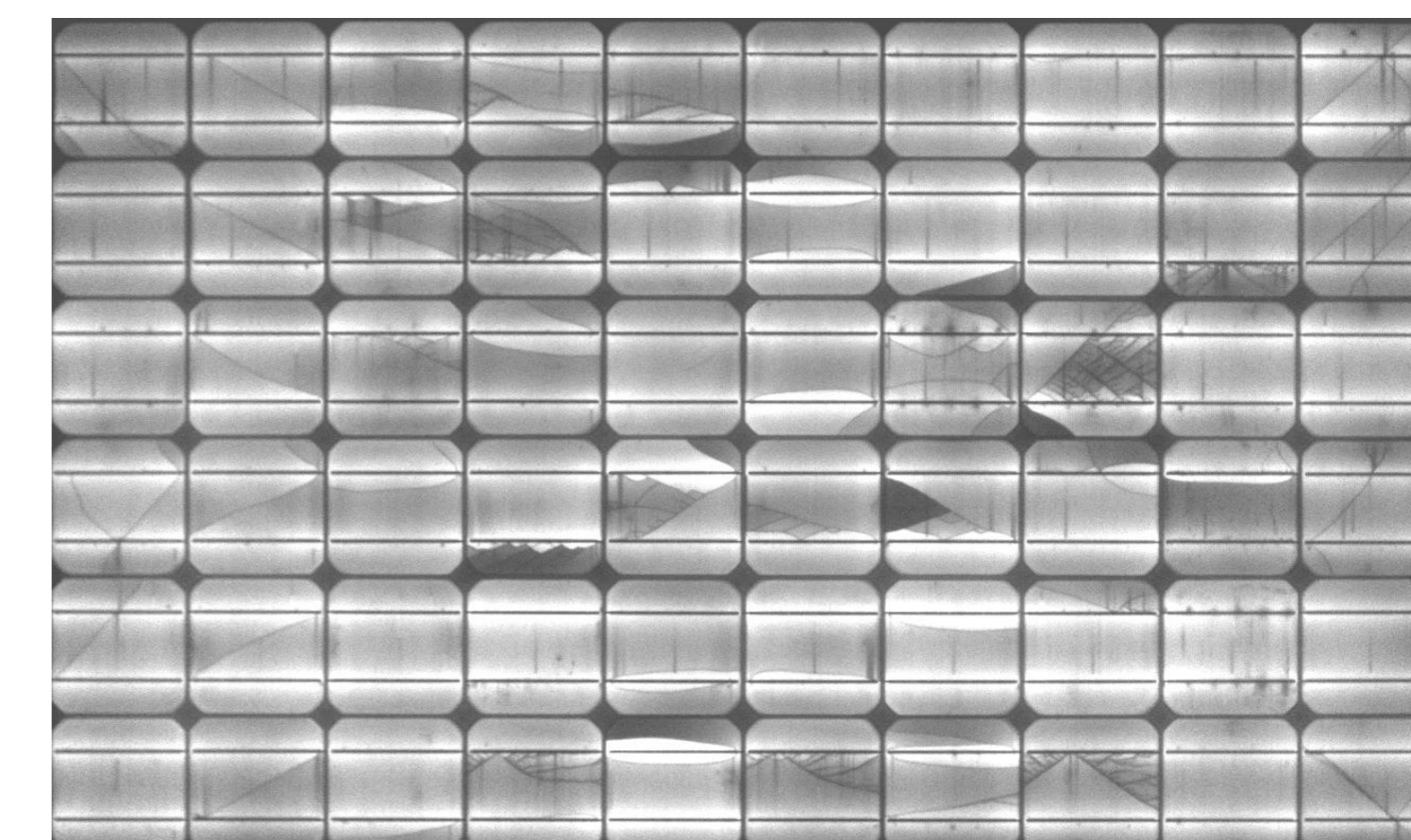


#### Mechanical stress

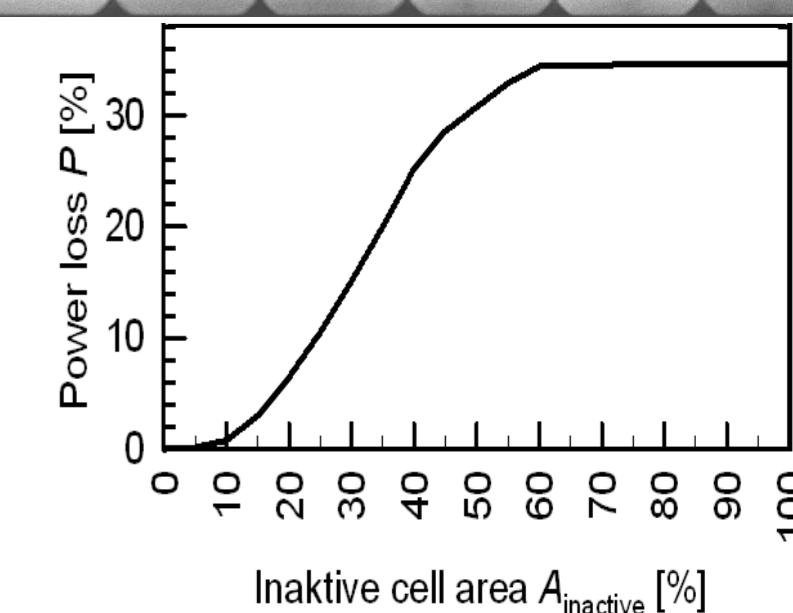
- Mechanical loads, e.g. wind, snow, transport and installation
- Changing environmental conditions, e.g. winter / summer, day / night



#### Crack propagation and

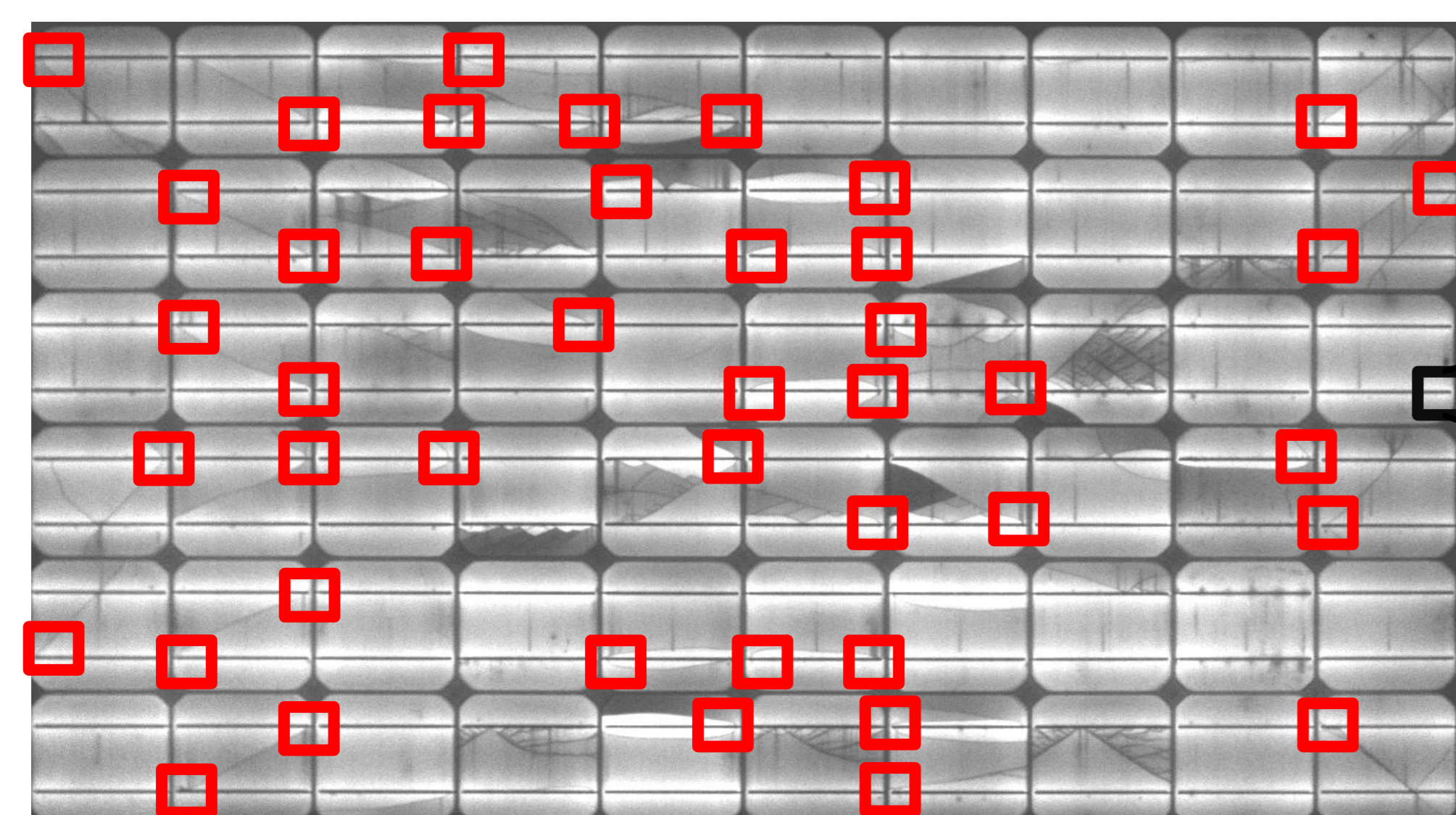


#### Power loss

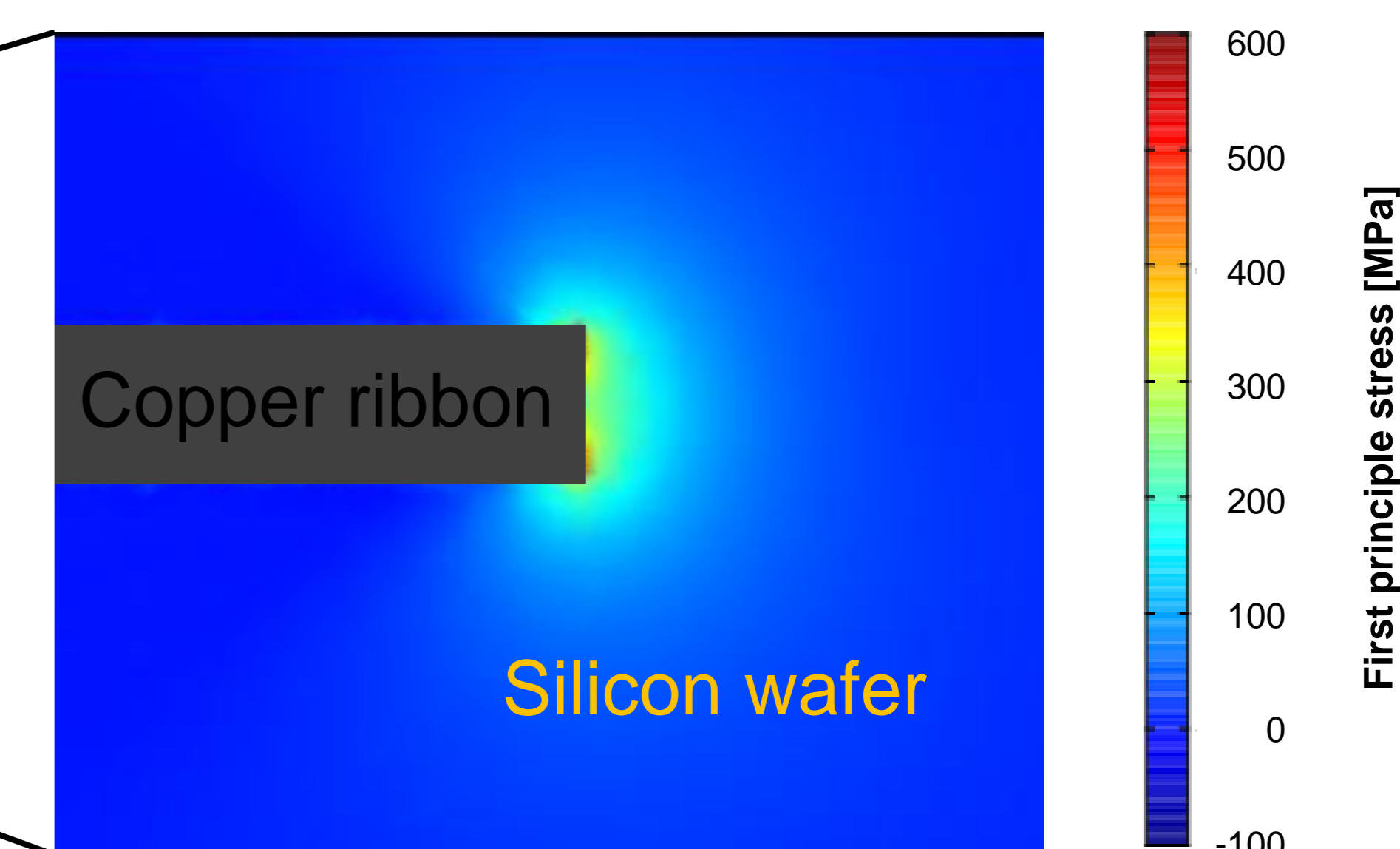


### Experimental challenge: Measuring internal stress (e.g.: by Raman spectroscopy)

#### End of busbars frequently origin of micro cracks



#### Soldering simulation of stress in silicon: 250 K cool down of copper ribbon

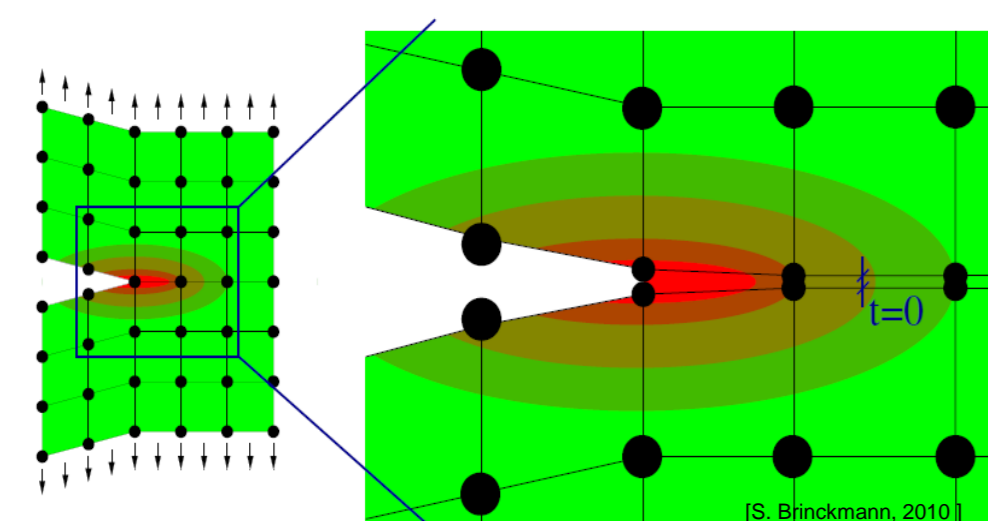


### Aim of project



#### Simulations

Thermo-mechanical multiscale simulation of crack initiation and propagation

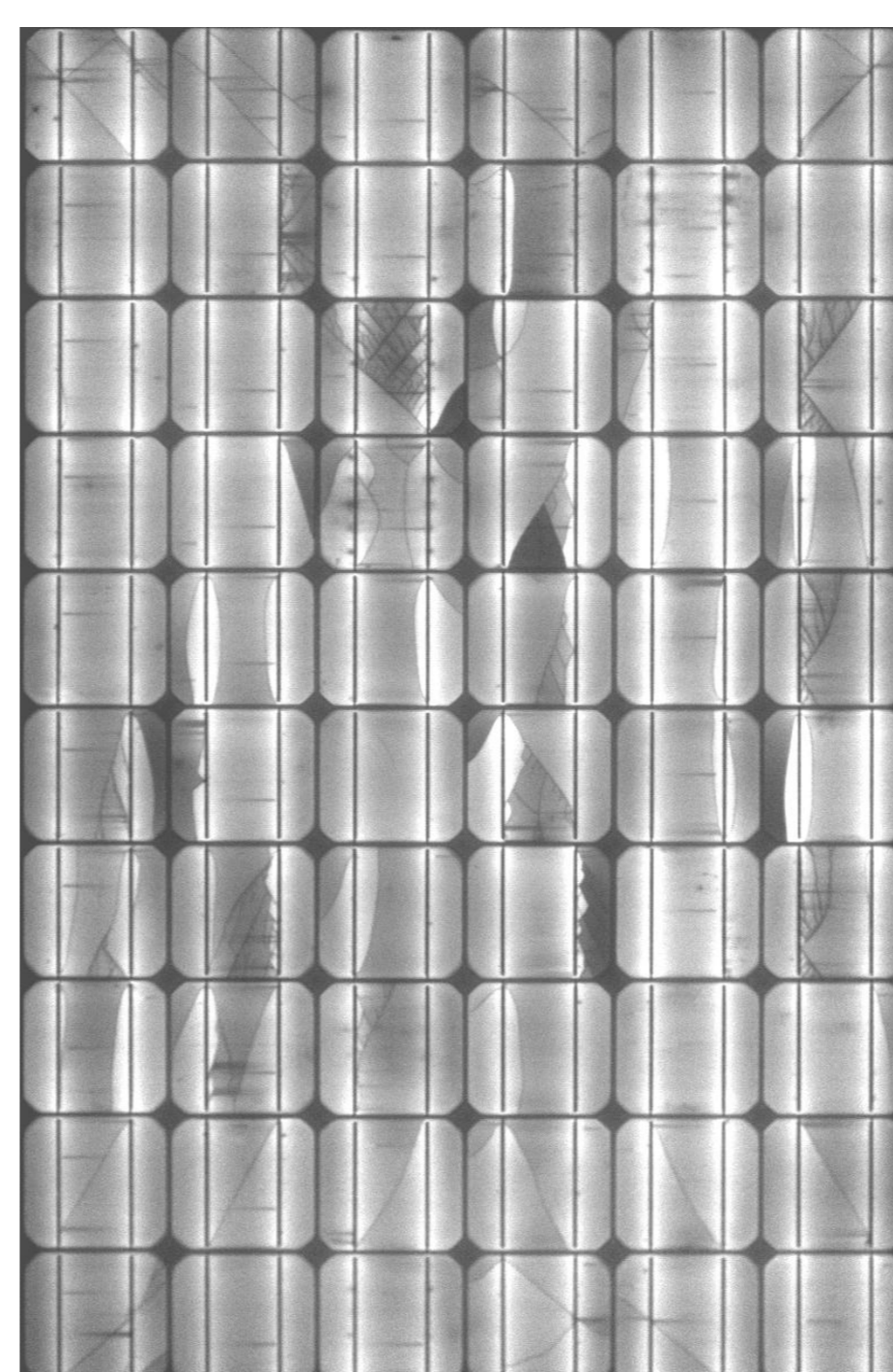


Micromechanical level

Wafer level



Module level



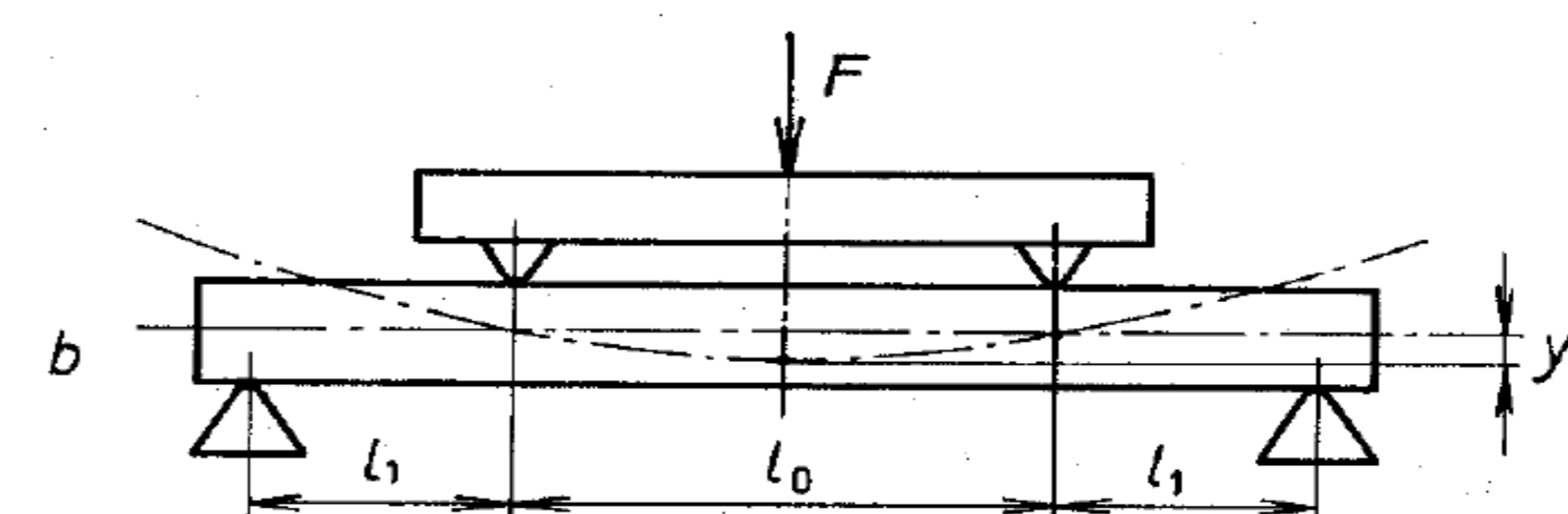
#### Reliable prediction of:

- Micro cracks
- Crack propagation
- Power loss

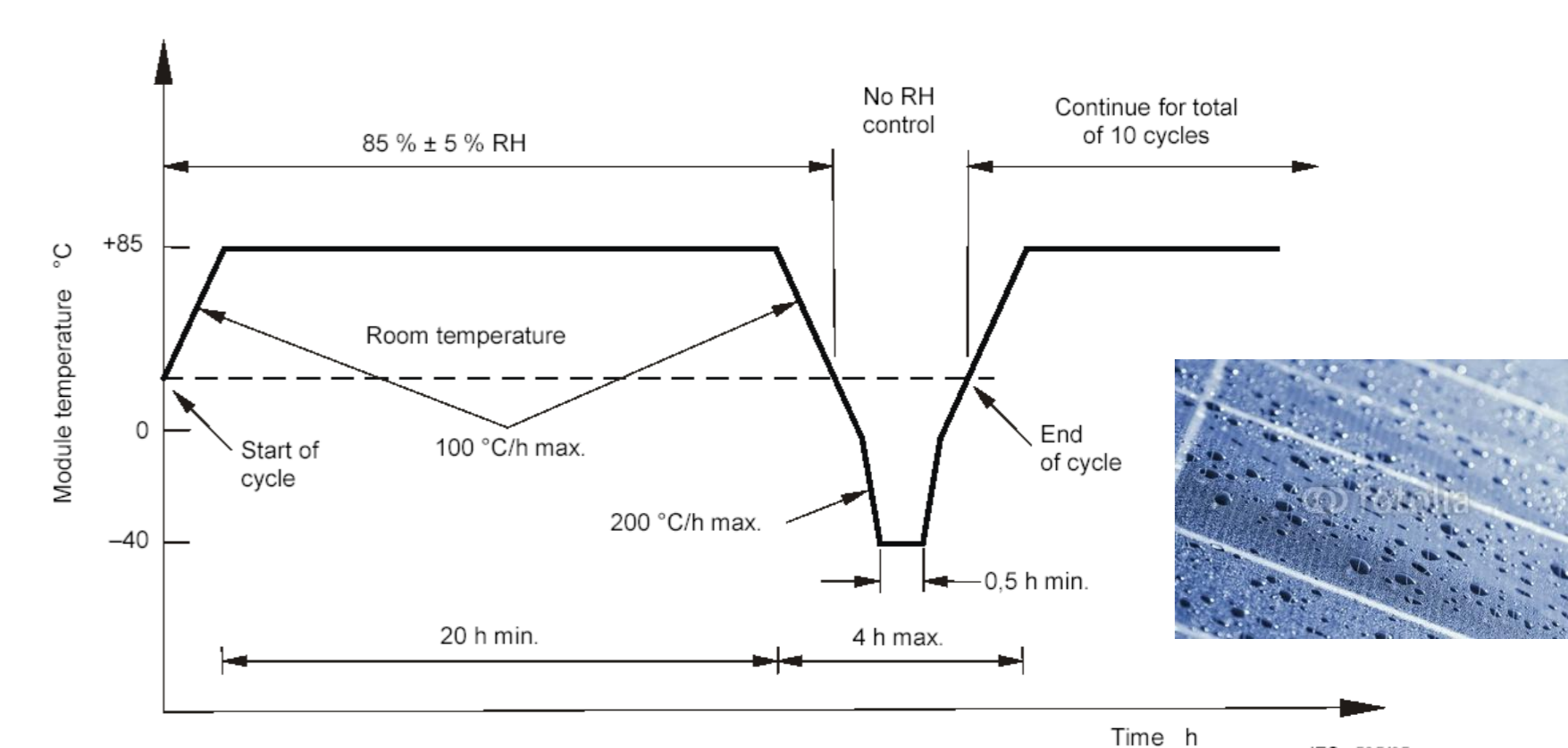
#### Experiments



Validation of simulations by e.g.



4 line bending of PV modules



Humidity freeze tests